

# [HEAT SINK STRUCTURE]

## Abstract

A heat sink structure suitable for a chip-packaging unit is provided. The heat sink structure includes a heat spreader and at least one arcuate spring. The heat spreader has a top surface and a bottom surface and the bottom surface covers over the chip-packaging unit. The arcuate spring is disposed between the bottom surface of the heat spreader and the chip-packaging unit, such that the arcuate spring is in contact with the back surface of a chip of the chip-packaging unit.